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T4-LDS-0113, Rev. 3 (121514)

Off-State Current (Peak Total Value) (3)

Derated linearly by 0.6 W/ $^{\circ}$ C for T_C > +25 $^{\circ}$ C.

wires and may be limited by pin diameter:

 $I_{DM} = 4 \times I_{D1}$ as calculated in note 2.

Source Current

1.

2.

3.

NOTES:

IDM

ls

 $I_{D} = \sqrt{\frac{T_{J} (max) - T_{C}}{R_{\theta JC} x R_{DS(on)} @ T_{J} (max)}}$

The following formula derives the maximum theoretical I_D limit. I_D is limited by package and internal

-50

-11

Ω

А

<u>Qualified Levels</u>: JAN, JANTX, and JANTXV



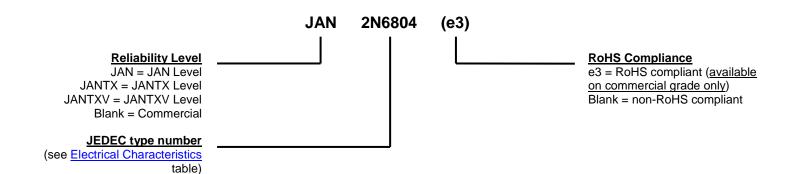
TO-204AA (TO-3) Package



MECHANICAL and PACKAGING

- CASE: TO-3 metal can.
- TERMINALS: Solder dipped (Sn63/Pb37) over nickel plated alloy 52. RoHS compliant matte-tin plating is also available.
- MARKING: Manufacturer's ID, part number, date code, ESD symbol.
- WEIGHT: Approximately 12.7 grams.
- See <u>Package Dimensions</u> on last page.

PART NOMENCLATURE



	SYMBOLS & DEFINITIONS					
Symbol	ol Definition					
di/dt	Rate of change of diode current while in reverse-recovery mode, recorded as maximum value.					
١ _F	Forward current					
R _G	Gate drive impedance					
V _{DD}	Drain supply voltage					
V _{DS}	Drain source voltage, dc					
V _{GS}	Gate source voltage, dc					



Parameters / Test Conditions	Symbol	Min.	Max.	Unit
OFF CHARACTERISTICS				
Drain-Source Breakdown Voltage $V_{GS} = 0 \text{ V}, I_D = -1.0 \text{ mA}$	V _{(BR)DSS}	-100		V
Gate-Source Voltage (Threshold) $V_{DS} \ge V_{GS}$, $I_D = -0.25 \text{ mA}$ $V_{DS} \ge V_{GS}$, $I_D = -0.25 \text{ mA}$, $T_J = +125 \text{ °C}$	V _{GS(th)1} V _{GS(th)2}	-2.0 -1.0	-4.0 -5.0	V
$V_{DS} \ge V_{GS}, I_D = -0.25 \text{ mA}, T_J = -55 \text{ °C}$ Gate Current $V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$ $V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}, T_J = +125 \text{ °C}$	V _{GS(th)3} I _{GSS1} I _{GSS2}		±100 ±200	nA
Drain Current $V_{GS} = 0 V, V_{DS} = -80 V$	I _{DSS1}		-25	μA
Drain Current $V_{GS} = 0 V, V_{DS} = -80 V, T_{J} = +125 $ °C	I _{DSS2}		0.25	mA
Static Drain-Source On-State Resistance V_{GS} = -10 V, I_D = -7 A pulsed	r _{DS(on)1}		0.30	Ω
Static Drain-Source On-State Resistance V_{GS} = -10 V, I_D = -11 A pulsed	r _{DS(on)2}		0.36	Ω
Static Drain-Source On-State Resistance $T_J = +125^{\circ}C$ $V_{GS} = -10 \text{ V}, I_D = -7 \text{ A pulsed}$	۲ _{DS(on)3}		0.55	Ω
Diode Forward Voltage $V_{GS} = 0 \text{ V}, \text{ I}_{S} = -11.0 \text{ A pulsed}$	V _{SD}		-4.7	V

ELECTRICAL CHARACTERISTICS @ $T_A = +25$ °C, unless otherwise noted

DYNAMIC CHARACTERISTICS

Parameters / Test Conditions	Symbol	Min.	Max.	Unit
Gate Charge:				
On-State Gate Charge V_{GS} = -10 V, I_D = -11 A, V_{DS} = -50 V	Q _{g(on)}		29.0	nC
Gate to Source Charge V_{GS} = -10 V, I_D = -11 A, V_{DS} = -50 V	Q _{gs}		7.1	nC
Gate to Drain Charge V_{GS} = -10 V, I_D = -11 A, V_{DS} = -50 V	Q_{gd}		21.0	nC



ELECTRICAL CHARACTERISTICS @ $T_A = +25 \text{ °C}$, unless otherwise noted (continued)

SWITCHING CHARACTERISTICS

Parameters / Test Conditions	Symbol	Min.	Max.	Unit
Turn-on delay time I_D = -11 A, V _{GS} = -10 V, R _G = 7.5 Ω , V _{DD} = -35 V	t _{d(on)}		60	ns
Rinse time $I_D = -11 \text{ A}, V_{GS} = -10 \text{ V}, R_G = 7.5 \Omega, V_{DD} = -35 \text{ V}$	t _r		140	ns
Turn-off delay time I_D = -11 A, V _{GS} = -10 V, R _G = 7.5 Ω , V _{DD} = -35 V	t _{d(off)}		140	ns
Fall time $I_D = -11 \text{ A}, V_{GS} = -10 \text{ V}, R_G = 7.5 \Omega, V_{DD} = -35 \text{ V}$	t _f		140	ns
Diode Reverse Recovery Time di/dt \leq 100 A/µs, V _{DD} \leq -50 V, I _F = -11 A	t _{rr}		250	ns



GRAPHS

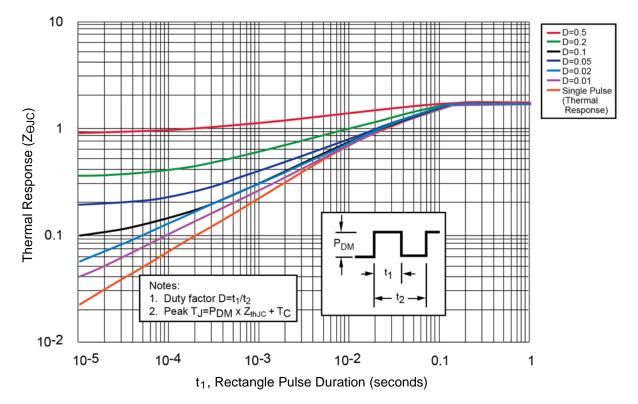


FIGURE 1 Transient Thermal impedance

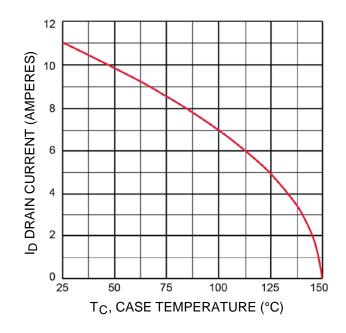
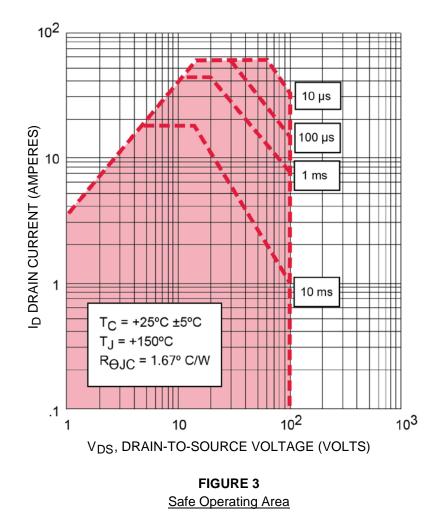


FIGURE 2 Maximum Drain Current vs Case Temperature

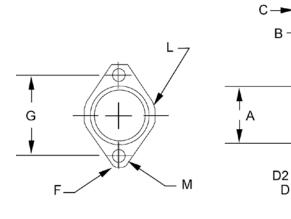


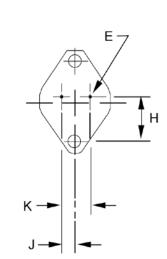
GRAPHS (continued)





PACKAGE DIMENSIONS



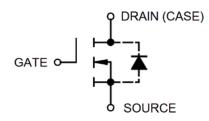


NOTE:

- 1. Dimensions are in inches.
- 2. Millimeters are given for general information only.
- 3. These dimensions should be measured at points .050 inch (1.27 mm) and .055 inch (1.40 mm) below seating plane. When gauge is not used measurement will be made at the seating plane.
- 4. The seating plane of the header shall be flat within .001 inch (0.03 mm) concave to .004 inch (0.10 mm) convex inside a .930 inch (23.62 mm) diameter circle on the center of the header and flat within .001 inch (0.03 mm) concave to .006 inch (0.15 mm) convex overall.
- 5. Mounting holes shall be deburred on the seating plane side.
- 6. Drain is electrically connected to the case.
- 7. In accordance with ASME Y14.5M, diameters are equivalent to Φx symbology.

DIM	INC	HES	MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	NULES
Α	-	.875	-	22.23	
В	.060	.135	1.52	3.43	
С	.250	.360	6.35	9.15	3
D	.312	.500	7.92	12.70	
D2	-	.050	-	1.27	
Е	.038	.043	0.97	1.10	DIA.
F	.131	.188	3.33	4.78	Radius
G	1.177	1.197	29.90	30.40	
Н	.655	.675	16.64	17.15	
J	.205	.225	5.21	5.72	3
Κ	.420	.440	10.67	11.18	3
L	.495	.525	12.57	13.34	Radius
Μ	.151	.161	3.84	4.09	DIA.

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